Managing to Learn — A3 Example #3: Reducing Assembly Defects — Mary’s Case

Title: Reduce Scratches in Assembly

1. Background
- Device-K is our next main product!
- Increase in variety of mounting/casing types
- Quality is a key success factor in assembly as well as in the chip process

2. Current state (Based on November data)

3. Target
(1) Zero scratches! 15% to Zero
(2) Reduce missed crimp! 10% to Zero → FPR ≥ 90%

4. Analysis
4-1. Hypothesis & go see -1: Assembly line #2?

5. Countermeasures and plan

6. Result & next challenge
(1) Remaining Defects
a) Scratches (2%)

(2) "Why" after current countermeasures
a) Broken head - why?
b) Burr - why?